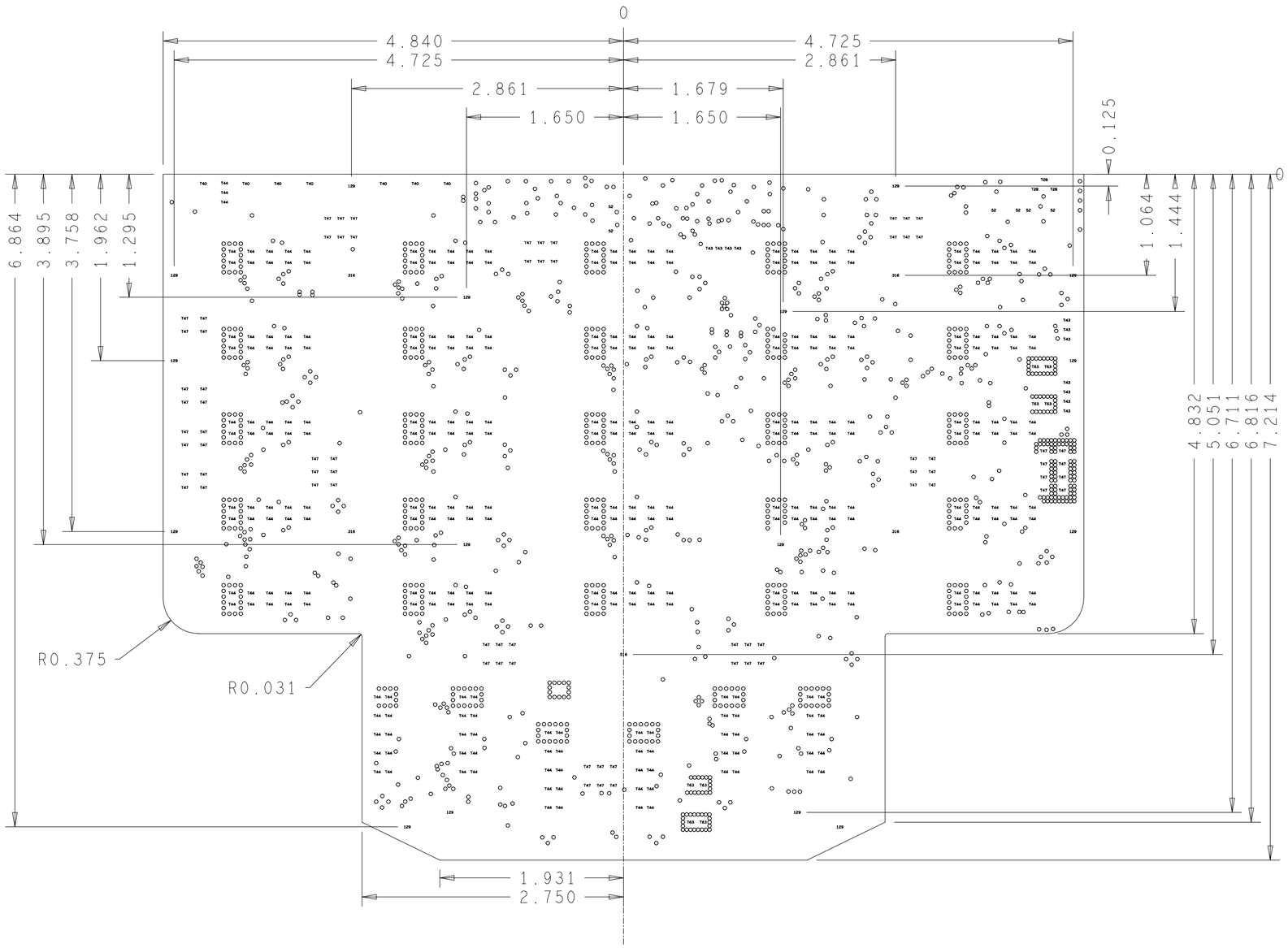
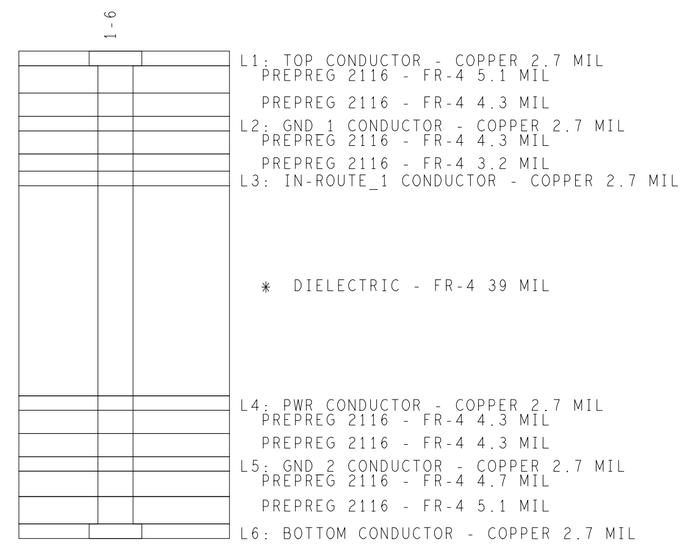
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:
   a. FR4 PER IPC 4101B/24 /26, OR /28.
   b. SIGNAL LAYERS TO BE 2 OZ. COPPER.
   c. PLANE LAYERS TO BE 2 OZ. COPPER.
   d. OVERALL THICKNESS TO BE 0.092" +/- 10%
4. LEGEND:
   a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:
   a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR RED, BOTH SIDES.
6. PLATING FINISH:
   a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
   ~~b. IMMERSION SILVER IAg~~
7. PROCESS ALLOWANCES:
   a. MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%.
   b. HOLE DIMENSIONS APPLY AFTER PLATING.
   c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
   d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
   e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
   f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
   g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.





DESIGN CROSS SECTION CHART
TOTAL THICKNESS 90.5 MIL

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
∘	10.0	PLATED	1342
T28	28.0	PLATED	3
T40	40.0	PLATED	7
T43	43.0	PLATED	11
T44	44.0	PLATED	313
T47	47.0	PLATED	72
52	52.0	PLATED	6
T63	63.0	PLATED	8
129	129.0	NON-PLATED	16
316	316.0	NON-PLATED	4
516	516.0	NON-PLATED	1

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	LRAUV - BATTERY PACK CONTROLLER
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA
	DESIGNED BY: DENIS KLIMOV		SIZE C / RELEASE A / DWG NO 10021057
	LAYOUT BY: JOSE ROSAL		SCALE 1-1 / SHEET 1-1